Single Unbuffered Inverter

The NLU1GU04 is an advanced high-speed CMOS unbuffered inverter in ultra-small footprint.

This device is well suited for use in oscillator, pulse–shaping and high input impedance amplifier applications. For digital applications, the NLU1GU04 is recommended.

The NLU1GU04 input and output structures provide protection when voltages up to 7.0 V are applied, irregardless of the supply voltage.

Features

- High Speed: $t_{PD} = 2.5 \text{ ns} (Typ) @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Pb-Free Package
- This is a Pb–Free Device

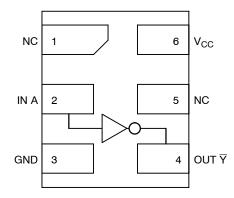


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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MARKING DIAGRAM





UDFN6 MU SUFFIX CASE 517AA

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U	= Device Marking
М	= Date Code

= Pb-Free Package

PIN ASSIGNMENT

1	NC
2	IN A
3	GND
4	OUT Y
5	NC
6	V _{CC}

FUNCTION TABLE

А	Ÿ
LH	HL

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V	
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	±20	mA
Ι _Ο	DC Output Source/Sink Current		±12.5	mA
I _{CC}	DC Supply Current Per Supply Pin		±25	mA
I _{GND}	DC Ground Current per Ground Pin	±25	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 Second	TBD	°C	
Τ _J	Junction Temperature Under Bias		TBD	°C
θ_{JA}	Thermal Resistance (Note 1)	UDFN6	TBD	°C/W
PD	Power Dissipation in Still Air at 85°C	UDFN6	TBD	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen	UL 94 V-0 @ 0.125 in		
V _{ESD}	ESD Withstand Voltage Human Body Mode (No M Charged	> 2000 > 200 N/A	V	
I _{LATCHUP}	Latchup Performance Above V_{CC} and Below GM	ND at 125 °C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

Tested to EIA / JESD22-A114-A.
 Tested to EIA / JESD22-A115-A.

4. Tested to JESD22-C101-A.

5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fail Rate V_{CC} = 3.3 V ± 0.3 V V_{CC} = 5.0 V ± 0.5 V	0 0	100 20	ns/V

NLU1GU04

DC ELECTRICAL CHARACTERISTICS

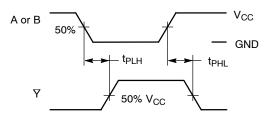
				T _A = 25 °C		TA = -	⊦85°C		55°C to 25°C		
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		1.65 2.3 to 5.5	0.85 x V _{CC} 0.80 x V _{CC}			0.85 x V _{CC} 0.80 x V _{CC}				V
V _{IL}	Low-Level Input Voltage		1.65 2.3 to 5.5			0.15 x V _{CC} 0.20 x V _{CC}		0.15 x V _{CC} 0.20 x V _{CC}		0.15 x V _{CC} 0.20 x V _{CC}	V
V _{OH}	High–Level Output Voltage	V_{IN} = V_{IH} or V_{IL} I_{OH} = -50 μ A	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V _{OL}	Low-Level Output Voltage	V_{IN} = V_{IH} or V_{IL} I_{OL} = 50 μ A	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		20		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

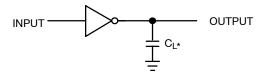
		V _{CC}	Test	т	A = 25 °	c	TA = -	+85°C	T _A = - to +1	-55°C 25°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay, Input A to \overline{V}	3.0 to	C _L = 15 pF		3.5	8.9		10.5		12	ns
t _{PHL}	Output Y	3.6	C _L = 50 pF		4.8	11.4		13		15.5	
		4.5 to	C _L = 15 pF		2.5	5.5		6.5		8.0	
		5.5	C _L = 50 pF		3.8	7.0		8.0		9.5	
C _{IN}	Input Capacitance				4	10		10		10	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	5.0			22						pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

NLU1GU04







*Includes all probe and jig capacitance. A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

ORDERING INFORMATION

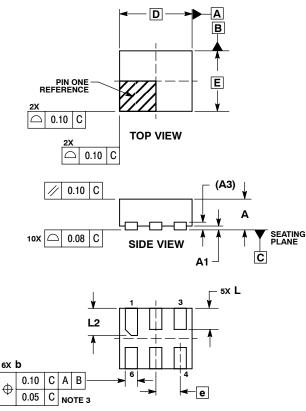
Device	Package	Shipping [†]
NLU1GU04MUTCG	UDFN6 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NLU1GU04

PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P CASE 517AA-01 ISSUE B

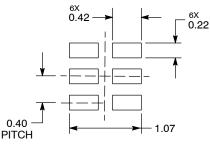


BOTTOM VIEW

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
A3	0.127 REF					
b	0.15	0.25				
D	1.20 BSC					
Е	1.00	BSC				
е	0.40	BSC				
L	0.30	0.40				
L2	0.40	0.50				

MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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